What is claimed is:

1. A sintering method for a W-Cu composite material without exuding of Cu comprising the steps of:

holding a W-Cu composite material prepared by compacting a W-Cu composite powder for 0.5~10 hours at 800~1083°C (except 1083°C) which is a Cu solid phase temperature range under a reduction atmosphere; and

increasing temperature to 1200 ~1400°C and thereby cooling without a holding time.

2. A sintering method for a W-Cu composite material without exuding of Cu comprising the steps of:

holding a W-Cu composite material prepared by compacting a W-Cu composite powder for 0.5~10 hours at 1083~1150°C which is just above a Cu melting point under a reduction atmosphere; and

increasing temperature to 1200 ~1400°C and thereby cooling without a holding time.

3. The method of claim 1 or 2, wherein the W-Cu composite powder prepared by a method disclosed in the Korean patent application No. 24857 in 2002 is prepared by mixing $WO_3/WO_{2.9}$ powder with CuO/Cu_2O, milling, and performing a heat treatment for reduction at a hydrogen atmosphere, and has a round shape of a certain size that W powder surrounds Cu powder.